

Product/Process Change Notification

N° 2021-045-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting product AUIR2085STR / product family HVIC Gen2

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-12-06.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Chairman of the Supervisory Board: Dr. Wolfgang Eder

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492

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Products affected

Please refer to attached affected product list 1_cip21045_A

Detailed change information

Subject: Several changes affecting product AUIR2085STR / product family HVIC Gen2

Reason/Motivation: Expansion of assembly production, final test and test platform capability to assure continuity of supply and enable flexible manufacturing.

Description	<u>Old</u>	<u>New</u>
PROCESS - WAFER PRODUCTION: New wafer diameter	Wafer diameter 150mm	Wafer diameter 200mm
PROCESS - WAFER PRODUCTION: New final wafer thickness	Wafer thickness 508um	Wafer thickness 355um
PROCESS - WAFER PRODUCTION: New / change of passivation or die coating (without bare die)	Passivation LTO end passivation	Passivation SION/USG/PSG/SION end passivation
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site	Wafer fab location Infineon Technologies Americas Corp., Temecula, United States	Wafer fab location Vanguard International Semiconductor Corporation, Hsinchu, Taiwan
PROCESS - ASSEMBLY: Change in leadframe dimensions	Leadframe dimension High density leadframe HDLF 32 columns X 8 rows	Leadframe dimension XDLF (extra high density leadframe) 40 columns X 15 rows
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	Mold compound CEL9220HF13V	Mold compound G700LS
PROCESS - ASSEMBLY: Change of product marking	Marking Indented mark for pin1 identification	Marking Laser marking for pin1 identification

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<p>PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site</p>	<p>Backend assembly location Carsem (M) Sdn Bhd, Ipoh, Malaysia</p>	<p>Backend assembly location Amkor Technology Malaysia, Sdn Bhd, Kuala Langat, Malaysia and Carsem (M) Sdn Bhd, Ipoh, Malaysia</p>
<p>EQUIPMENT: Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process</p>	<p>Backend assembly equipment Carsem (M) Sdn Bhd, Ipoh, Malaysia equipment pool</p>	<p>Backend assembly equipment Amkor Technology Malaysia, Sdn Bhd, Kuala Langat, Malaysia equipment pool</p>
<p>EQUIPMENT: Change in final test equipment type leading to a different test concept</p>	<p>Test platform ASL1000</p>	<p>Test platform ETS88</p>
<p>TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site</p>	<p>Wafer test location Infineon Technologies Americas Corp., Temecula, United States Final test location Carsem (M) Sdn Bhd, Ipoh, Malaysia</p>	<p>Wafer test location ETREND Hightech Corp, Hsin-Chu, Taiwan Final test location Amkor Technology Malaysia, Sdn Bhd, Kuala Langat, Malaysia and Carsem (M) Sdn Bhd, Ipoh, Malaysia</p>

Product identification

Traceability assured via date code.
No change in SP ordering number

Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in form, fit and function expected.

DeQuMa-ID(s): SEM-PW-02 / SEM-PW-03 / SEM-PW-08 / SEM-PW-13 / SEM-PA-03 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-EQ-02 / SEM-EQ-03 / SEM-TF-01

Attachments

1_cip21045_A affected product list

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Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2022-04-25
Last order date (LOD) [2]	2022-04-25
Last delivery date (LDD) [3]	2023-04-25

[1] Provided date or earlier after customer approval

[2] Last time buy volume to be placed latest until LOD

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.



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Sales name	SP number	OPN	Package
AUIR2085STR	SP001514866	AUIR2085STR	PG-DSO-8-904